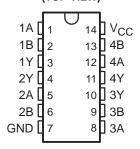
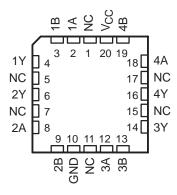
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Inverting Outputs Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}
- Typical t_{pd} = 10 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

SN54HC266 . . . J OR W PACKAGE SN74HC266 . . . D, N, OR NS PACKAGE (TOP VIEW)



SN54HC266 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'HC266 devices have four independent 2-input exclusive-NOR gates and feature open-drain outputs. They perform the Boolean function $Y = \overline{A \otimes B}$ or $Y = \overline{AB} + \overline{AB}$ in positive logic.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC266N	SN74HC266N
-40°C to 85°C		Tube of 50	SN74HC266D	
	SOIC - D	Reel of 2500	SN74HC266DR	HC266
		Reel of 250	SN74HC266DT	
	SOP - NS	Reel of 2000	SN74HC266NSR	HC266
	CDIP – J	Tube of 25	SNJ54HC266J	SNJ54HC266J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC266W	SNJ54HC266W
	LCCC – FK	Tube of 55	SNJ54HC266FK	SNJ54HC266FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN54HC266, SN74HC266 QUADRUPLE 2-INPUT EXCLUSIVE-NOR GATES WITH OPEN-DRAIN OUTPUTS

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FUNCTION TABLE

INP	UTS	OUTPUT				
Α	В	Υ				
L	L	Н				
L	Н	L				
Н	L	L				
Н	Н	Н				

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (se	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	86°C/W
•••	N package	80°C/W
	NS package	76°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC266		66	SN74HC266				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		V _{CC} = 6 V	4.2		7	4.2				
		V _{CC} = 2 V		0.5				0.5		
VIL	Low-level input voltage	V _{CC} = 4.5 V		1.35				1.35	V	
		VCC = 6 V		1.8				1.8		
VI	Input voltage		0 /	5	Vcc	0		VCC	V	
٧o	Output voltage		.0 ^C)	Vcc	0		Vcc	V	
		V _{CC} = 2 V	Q		1000			1000		
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		VCC = 6 V			400			400		
TA	Operating free-air temperature	•	-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS		V	T _A = 25°C			SN54HC266		SN74HC266		
PARAMETER	TEST CC	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
loн	$V_I = V_{IH} \text{ or } V_{IL}$	AO = ACC	6 V		0.01	0.5		10		5	μΑ
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1	-6	0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26	74,	0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26	27/	0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100	70,	±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			2	d	40		20	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

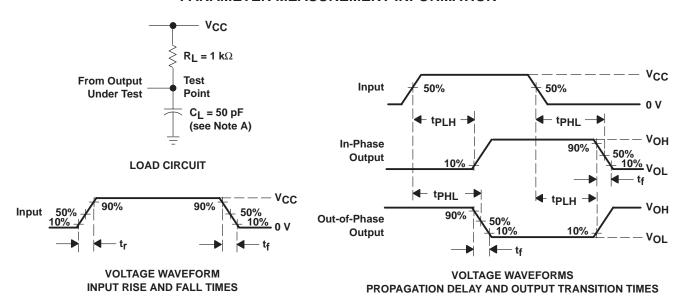
DADAMETER	FROM	то	,	T,	ղ = 25°C	;	SN54HC	266	SN74H	IC266	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	tPLH A or B Y		2 V		60	125		190		155	
tPLH		Υ	4.5 V		13	25		38		31	ns
			6 V		10	23		32		26	
		Y	2 V		60	100	Q	150		125	
tPHL	A or B		4.5 V		13	20	7.	30		25	ns
			6 V		10	17	2	25		21	
			2 V		28	75	0	110		95	
t _t		Y	4.5 V		8	15	Q	22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	35	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC266D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC266NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC266NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC266NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

18-Sep-2008

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC266DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC266NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC266DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74HC266NSR	SO	NS	14	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

